

IN THE SPECIFICATION:

Page 1, revise Lines 7-14 to read as follows:

- -BACKGROUND TECHNICAL FIELD OF THE INVENTION AND
DESCRIPTION OF PRIOR ART

The present invention relates to an apparatus for cleaving thin rods of glass or quartz (silica) having a diameter below 1 mm as well as a method for carrying out such a cleaving according to the preambles of the appended independent apparatus and method claims.- -; and

Revise Page 1, Line 36 to Page 2, Line 9 to read as follows:

- -An apparatus according to the preamble of claim 1 is already known through US-patent 4 790 465. By using such a driving means for superimposing a relatively small-amplitude vibratory component of movement towards and away from the cleaving point to a relatively steady movement towards the cleaving point it has turned out that an anvil for supporting the optical fibre at the cleaving point is superfluous. This means that it will be easier to accurately monitor the cleaving process for improving the result thereof. However, it is emphasized that the present invention is not restricted to an apparatus having no such anvil, but also apparatuses with a supporting anvil are conceivable.- -